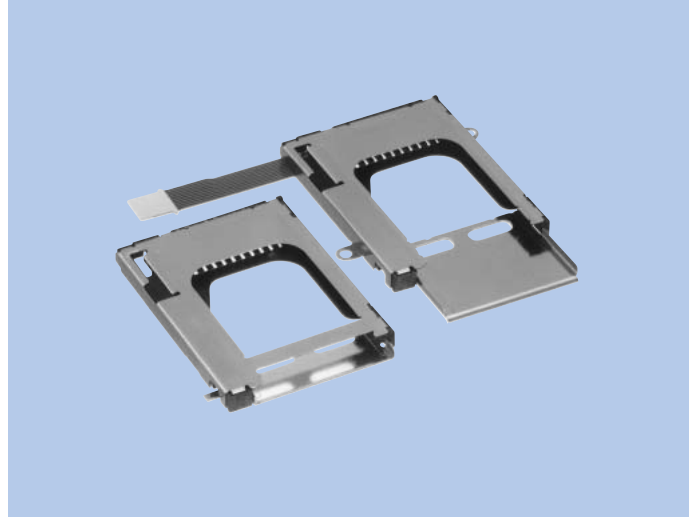


Memory Stick™ Connectors CIM-E31 Series

FEATURES

1. Memory Stick™ connector.
2. Fantastic touch! With push-in push-out eject function.
3. Supports presence or absence of card detection switch.
4. Ideal for portable equipment! Ultra-small, ultra-thin, and only 3.5mm high, with coupled length of 51.8mm.
5. SMT and FPC (FPC is customizable) types are available.
6. Half-lock mechanism prevents card falling out, and full-lock mechanism operates when coupled.

* Memory Stick™ is a registered trademark of SONY Corporation.



HOW TO ORDER

E31-010-21 0-A G K A-

1 2 3 4 5 6 7 8 9

1. Series No. (E31)
2. No. of contacts (010 : 10pins)
3. Housing material (21 : LCP resin)
4. Housing UL grade (0 : UL94V-0)
5. Contact plating (A : Gold)
6. Contact plating thickness (G : 0.3μm)
7. Contact style (K : FPC, G : Angle SMT)
8. Package (E : Tray)
9. Supplementary symbol

SPECIFICATIONS

ELECTRICAL CHARACTERISTICS

Rated Voltage	AC 50V (rms)
Rated Current	0.5A
Withstanding Voltage	500V AC (rms) 1minute
Insulation Resistance	1000MΩ min. (at 500V DC)
Contact Resistance	Initial: 40mΩ max.; after testing: 80mΩ max.

MECHANICAL CHARACTERISTICS

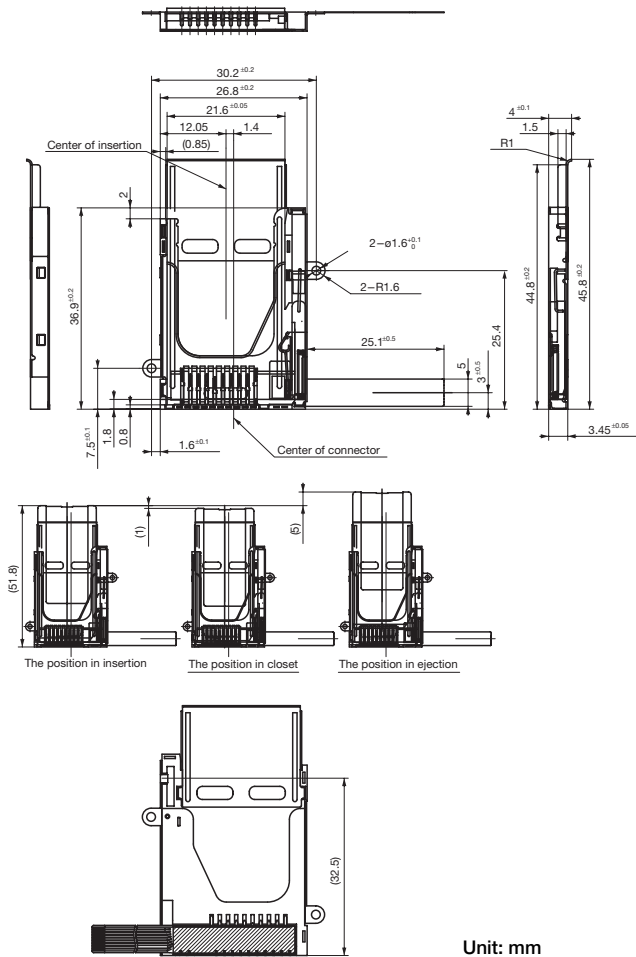
Life (Matching Cycle)	12,000 times
Card Insertion Force	4.9N (0.5kgf)~8.83N (0.9kgf)
Eject Force	4.9N (0.5kgf)~8.83N (0.9kgf)
Using Temperature Range	-20~+60°C

MATERIAL & FINISH

Component Parts	FPC Type		SMT Type	
	Material	Finish	Material	Finish
Housing	LCP resin	(Black)	LCP resin	(Black)
Contact	Copper Alloy	Gold plating	Copper Alloy	Gold plating
Plate	SUS	-	SUS	-
Half Lock	SUS	-	SUS	-
Slider Case	PPA resin	(Black)	PPA resin	(Black)
Coil Spring	SUS	-	SUS	-
Lock Pin	SUS	-	SUS	-
Switch A	Copper Alloy	Gold plating	Copper Alloy	Gold plating
Switch B	Copper Alloy	Gold plating	Copper Alloy	Gold plating
Lock Spring	SUS	-	SUS	-
Guide Plate	SUS	-	SPTE	Tin plating
Insulated Sheet	PET	-	PET	-

DIMENSIONS

FPC Type



SMT Type

